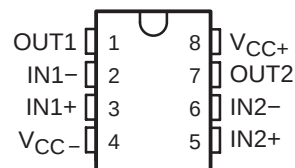


TL3414A DUAL HIGH-OUTPUT-CURRENT OPERATIONAL AMPLIFIER

SLOS453A – DECEMBER 2004 – REVISED JANUARY 2005

- Single/Dual Power-Supply Operation
- High Output Current . . . 70 mA, $V_{CC+} = 5\text{ V}$
- Wide Operating Voltage . . . 3 V to 15 V (Single Supply)
- Ideal for Headphone Drivers

D (SOIC), P (PDIP), OR PW (TSSOP) PACKAGE
(TOP VIEW)



description/ordering information

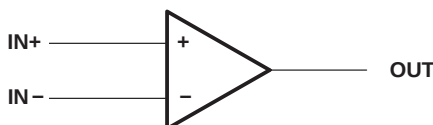
The TL3414A device is a dual operational amplifier that can be operated with single or dual power supplies. In addition to high gain and high output voltage swing, it is capable of driving a 70-mA load, making it ideally suited for simple, low-cost audio-amplifier applications, such as headphone amplifiers in DVD and CDRW applications.

ORDERING INFORMATION

T_A	PACKAGE [†]		ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	PDIP (P)	Tube of 50	TL3414AIP	TL3414AIP
	SOIC (D)	Tube of 75	TL3414AID	Z3414A
		Reel of 2500	TL3414AIDR	
	TSSOP (PW)	Tube of 150	TL3414AIPW	Z3414A
		Reel of 2000	TL3414AIPWR	

[†] Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

symbol (each amplifier)



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

**TEXAS
INSTRUMENTS**

POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

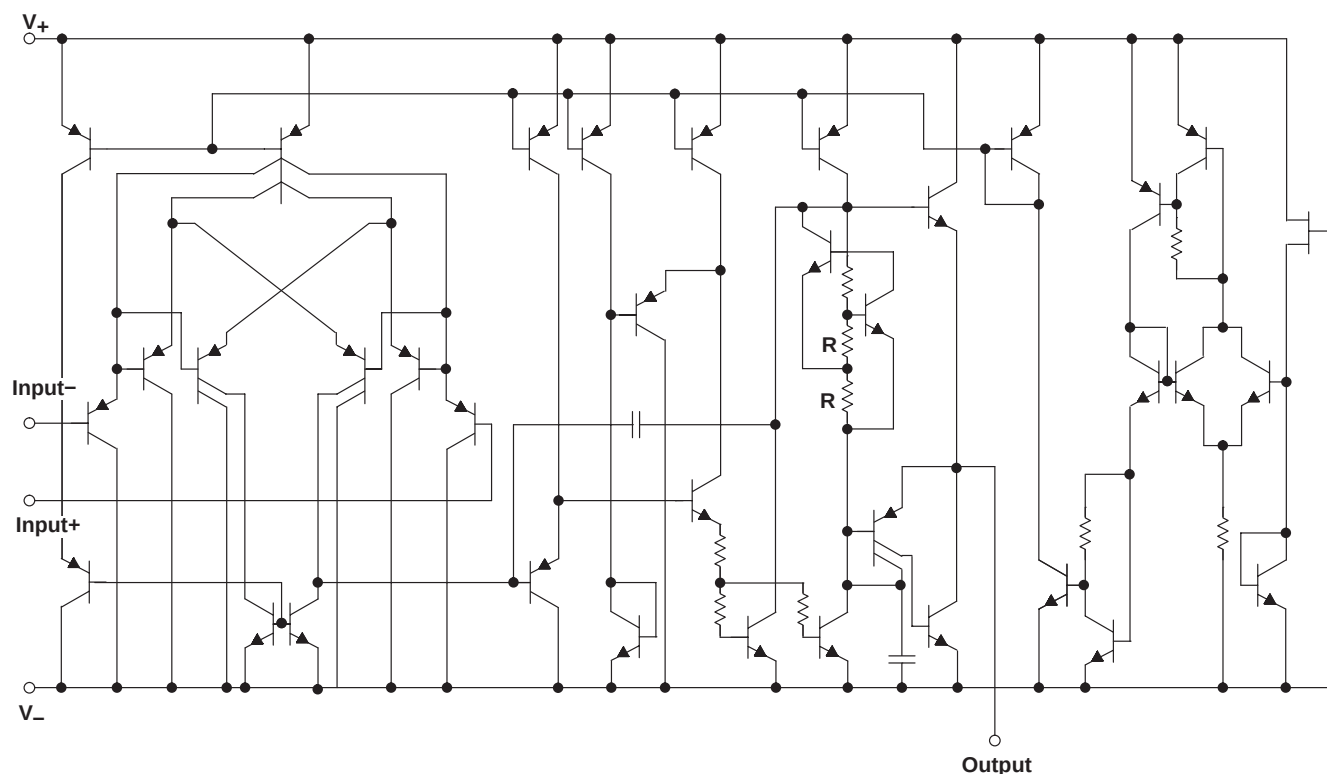
Copyright © 2005, Texas Instruments Incorporated

TL3414A

DUAL HIGH-OUTPUT-CURRENT OPERATIONAL AMPLIFIER

SLOS453A – DECEMBER 2004 – REVISED JANUARY 2005

simplified schematic



absolute maximum ratings over operating free-air temperature range (unless otherwise noted)[†]

Supply voltage, V_{CC+} (single supply)	15 V
Supply voltage, V_{CC-} (single supply)	0 V
Supply voltage, V_{CC+} (dual supply)	7.5 V
Supply voltage, V_{CC-} (dual supply)	-7.5 V
Supply voltage, (V_{CC-} to V_{CC+})	15 V
Input voltage, either input (see Note 1)	V_{CC-} or V_{CC+}
Input current (see Note 2)	± 10 mA
Duration of output short circuit (see Note 3)	Unlimited
Package thermal impedance, θ_{JA} (see Notes 4 and 5): D package	97°C/W
P package	85°C/W
PW package	149°C/W
Operating virtual junction temperature, T_J	150°C
Storage temperature range, T_{stg}	-40°C to 125°C

[†] Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

- NOTES:
1. The magnitude of the input voltage must never exceed the magnitude of the supply voltage.
 2. Excessive input current will flow if a differential input voltage in excess of approximately 0.6 V is applied between the inputs, unless some limiting resistance is used.
 3. The output may be shorted to ground or either power supply. Temperature and/or supply voltages must be limited to ensure the maximum dissipation rating is not exceeded.
 4. Maximum power dissipation is a function of $T_J(\max)$, θ_{JA} , and T_A . The maximum allowable power dissipation at any allowable ambient temperature is $P_D = (T_J(\max) - T_A)/\theta_{JA}$. Operating at the absolute maximum T_J of 150°C can impact reliability.
 5. The package thermal impedance is calculated in accordance with JESD 51-7.

TL3414A

DUAL HIGH-OUTPUT-CURRENT OPERATIONAL AMPLIFIER

SLOS453A – DECEMBER 2004 – REVISED JANUARY 2005

recommended operating conditions

	MIN	MAX	UNIT
V_{CC} Supply voltage (single supply)	3	15	V
V_{CC+} Supply voltage (dual supply)	1.5	7.5	V
V_{CC-} Supply voltage (dual supply)	-1.5	-7.5	V
V_{ID} Differential input voltage		15	V
V_I Input voltage	-0.3	15	V
T_A Operating free-air temperature range	-40	85	°C

DC electrical characteristics, $V_{CC+} = 5\text{ V}$, $V_{CC-} = 0\text{ V}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{IO}	Input offset voltage	R _S = 0 Ω		2	5	mV
I _{IO}	Input offset current			15	100	nA
I _{IB}	Input bias current			300	600	nA
A _{VD}	Large-signal differential voltage amplification	R _L = 2 kΩ	77	100		dB
V _{ICR}	Common-mode input voltage range		V _{CC+} − 2V			V
V _{OM}	Output voltage swing	R _L > 2 kΩ, V _{CC+} = 5 V	3.5			V
		I _O = 70 mA, V _{CC+} = 5 V	3.2			
CMRR	Common-mode rejection ratio		70	79		dB
k _{SVR} [†]	Supply-voltage rejection ratio		80	90		dB
I _{CC}	Supply current (all amplifiers)	R _L = open circuit (full temperature range)	3	4	6	mA

† Measured with $V_{CC\pm}$ differentially and simultaneously varied from 5 V to 8.6 V

AC electrical characteristics, $V_{CC+} = 5\text{ V}$, $V_{CC-} = 0\text{ V}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER	TEST CONDITIONS	TYP	UNIT
SR Slew rate at unity gain		0.83	V/ μs
GBW Gain bandwidth product		1.1	MHz
V_n Equivalent input noise voltage	$f = 1\text{ kHz}$	18	nV/ $\sqrt{\text{Hz}}$

DC electrical characteristics, $V_{CC+} = 8.6\text{ V}$, $V_{CC-} = 0\text{ V}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
V _{IO}	Input offset voltage	R _S = 0 Ω		2	5	mV
I _{IO}	Input offset current			15	100	nA
I _{IB}	Input bias current			300	600	nA
A _{VD}	Large-signal differential voltage amplification	R _L = 2 kΩ	88	105		dB
V _{ICR}	Common-mode input voltage range		V _{CC+} − 2V			V
V _{OM}	Output voltage swing	R _L > 2 kΩ, V _{CC+} = 8.6 V	7			V
		I _O = 70 mA, V _{CC+} = 8.6 V	6.7			
CMRR	Common-mode rejection ratio		80	90		dB
k _{SVR} [†]	Supply-voltage rejection ratio		80	90		dB
I _{CC}	Supply current (all amplifiers)	R _L = open circuit (full temperature range)	3	4	6	mA

† Measured with $V_{CC\pm}$ differentially and simultaneously varied from 5 V to 8.6 V



TL3414A

DUAL HIGH-OUTPUT-CURRENT OPERATIONAL AMPLIFIER

SLOS453A – DECEMBER 2004 – REVISED JANUARY 2005

AC electrical characteristics, $V_{CC+} = 8.6\text{ V}$, $V_{CC-} = 0\text{ V}$, $T_A = 25^\circ\text{C}$ (unless otherwise noted)

PARAMETER		TEST CONDITIONS	TYP	UNIT
SR	Slew rate at unity gain		1.3	V/ μs
GBW	Gain bandwidth product		2	MHz
V_n	Equivalent input noise voltage	$f = 1\text{ kHz}$	18	$\text{nV}/\sqrt{\text{Hz}}$



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

PACKAGING INFORMATION

Orderable part number	Status (1)	Material type (2)	Package Pins	Package qty Carrier	RoHS (3)	Lead finish/ Ball material (4)	MSL rating/ Peak reflow (5)	Op temp (°C)	Part marking (6)
TL3414AID	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3414A
TL3414AID.A	Active	Production	SOIC (D) 8	75 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3414A
TL3414AIDR	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3414A
TL3414AIDR.A	Active	Production	SOIC (D) 8	2500 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3414A
TL3414AIPW	Active	Production	TSSOP (PW) 8	150 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3414A
TL3414AIPW.A	Active	Production	TSSOP (PW) 8	150 TUBE	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3414A
TL3414AIPWR	Active	Production	TSSOP (PW) 8	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3414A
TL3414AIPWR.A	Active	Production	TSSOP (PW) 8	2000 LARGE T&R	Yes	NIPDAU	Level-1-260C-UNLIM	-40 to 85	Z3414A

⁽¹⁾ **Status:** For more details on status, see our [product life cycle](#).

⁽²⁾ **Material type:** When designated, preproduction parts are prototypes/experimental devices, and are not yet approved or released for full production. Testing and final process, including without limitation quality assurance, reliability performance testing, and/or process qualification, may not yet be complete, and this item is subject to further changes or possible discontinuation. If available for ordering, purchases will be subject to an additional waiver at checkout, and are intended for early internal evaluation purposes only. These items are sold without warranties of any kind.

⁽³⁾ **RoHS values:** Yes, No, RoHS Exempt. See the [TI RoHS Statement](#) for additional information and value definition.

⁽⁴⁾ **Lead finish/Ball material:** Parts may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

⁽⁵⁾ **MSL rating/Peak reflow:** The moisture sensitivity level ratings and peak solder (reflow) temperatures. In the event that a part has multiple moisture sensitivity ratings, only the lowest level per JEDEC standards is shown. Refer to the shipping label for the actual reflow temperature that will be used to mount the part to the printed circuit board.

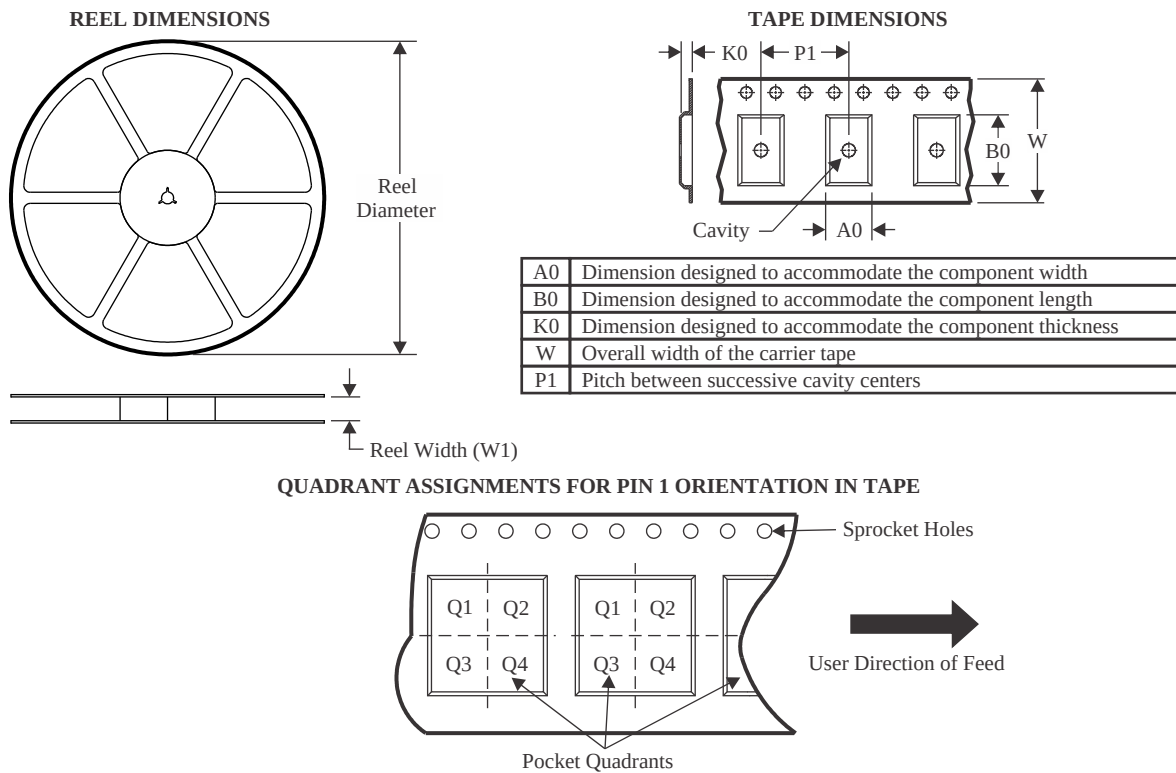
⁽⁶⁾ **Part marking:** There may be an additional marking, which relates to the logo, the lot trace code information, or the environmental category of the part.

Multiple part markings will be inside parentheses. Only one part marking contained in parentheses and separated by a "~" will appear on a part. If a line is indented then it is a continuation of the previous line and the two combined represent the entire part marking for that device.

Important Information and Disclaimer: The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

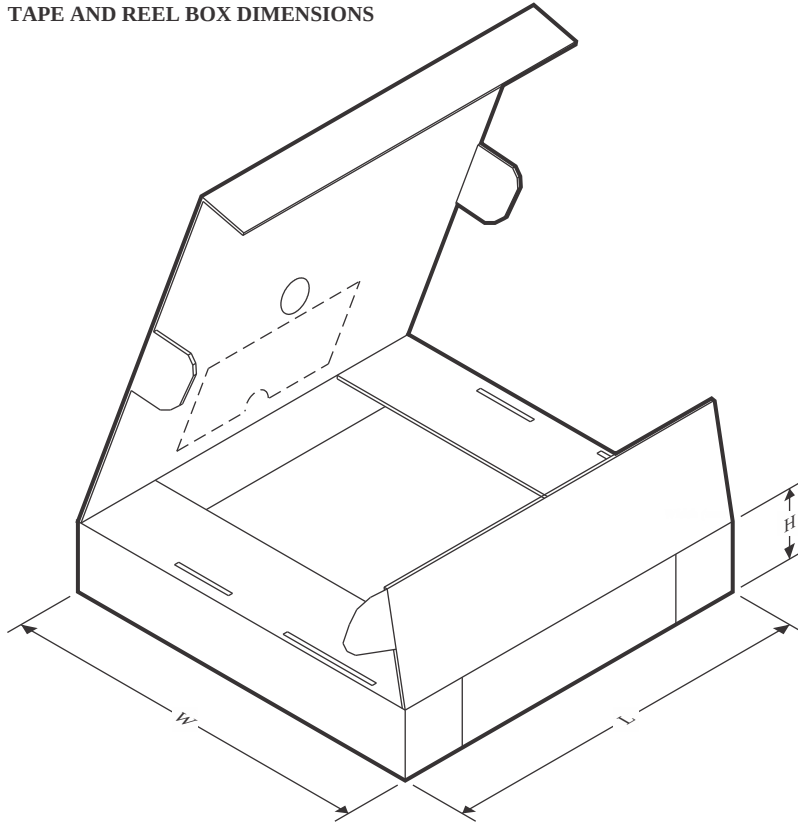
TAPE AND REEL INFORMATION



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TL3414AIDR	SOIC	D	8	2500	330.0	12.4	6.4	5.2	2.1	8.0	12.0	Q1
TL3414AIPWR	TSSOP	PW	8	2000	330.0	12.4	7.0	3.6	1.6	8.0	12.0	Q1

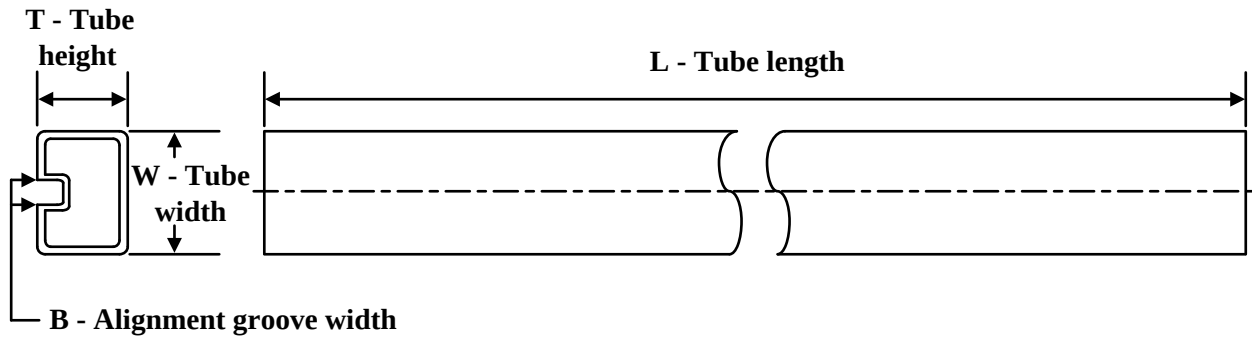
TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TL3414AIDR	SOIC	D	8	2500	340.5	338.1	20.6
TL3414AIPWR	TSSOP	PW	8	2000	353.0	353.0	32.0

TUBE



*All dimensions are nominal

Device	Package Name	Package Type	Pins	SPQ	L (mm)	W (mm)	T (μm)	B (mm)
TL3414AID	D	SOIC	8	75	507	8	3940	4.32
TL3414AID.A	D	SOIC	8	75	507	8	3940	4.32
TL3414AIPW	PW	TSSOP	8	150	530	10.2	3600	3.5
TL3414AIPW.A	PW	TSSOP	8	150	530	10.2	3600	3.5

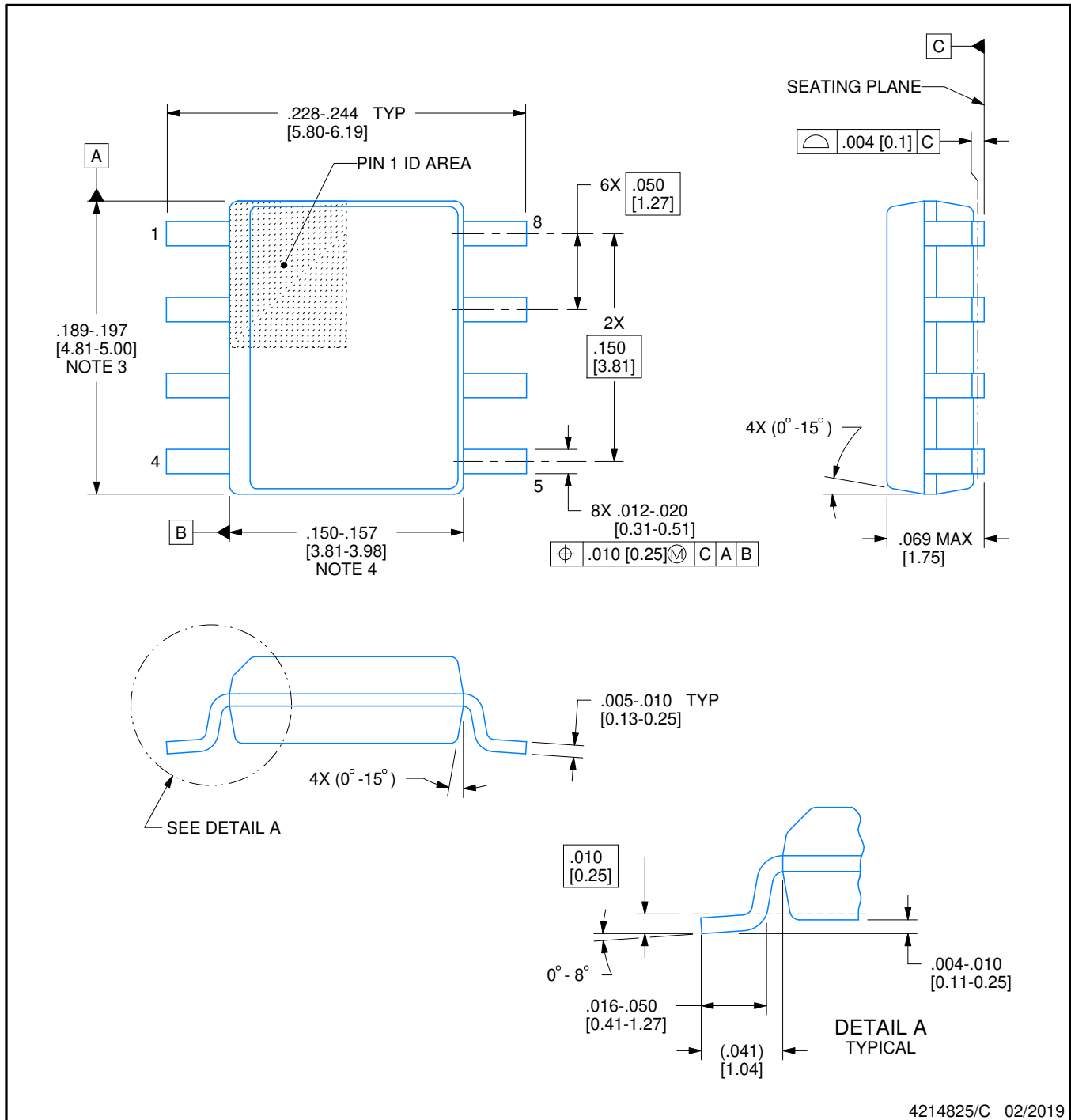


D0008A

PACKAGE OUTLINE

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



4214825/C 02/2019

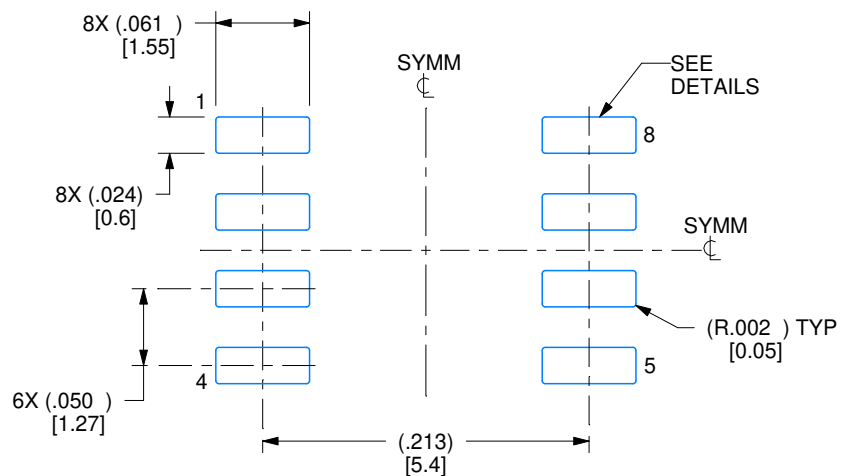
NOTES:

1. Linear dimensions are in inches [millimeters]. Dimensions in parenthesis are for reference only. Controlling dimensions are in inches. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed .006 [0.15] per side.
4. This dimension does not include interlead flash.
5. Reference JEDEC registration MS-012, variation AA.

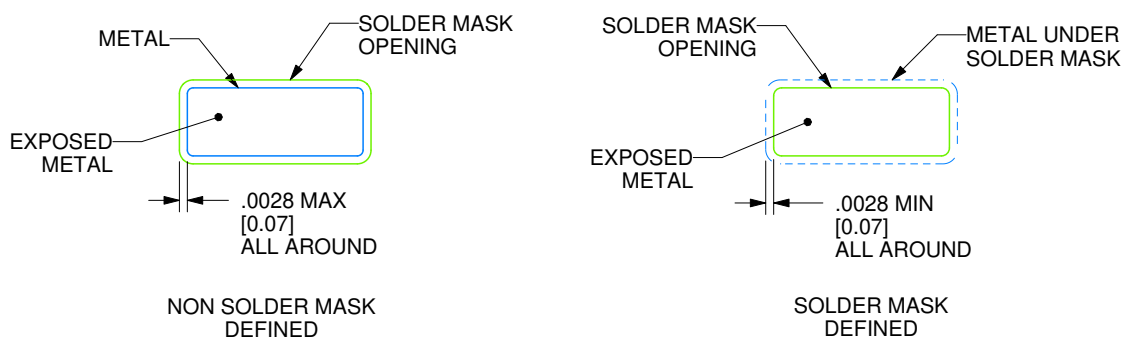
D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



LAND PATTERN EXAMPLE
EXPOSED METAL SHOWN
SCALE:8X



SOLDER MASK DETAILS

4214825/C 02/2019

NOTES: (continued)

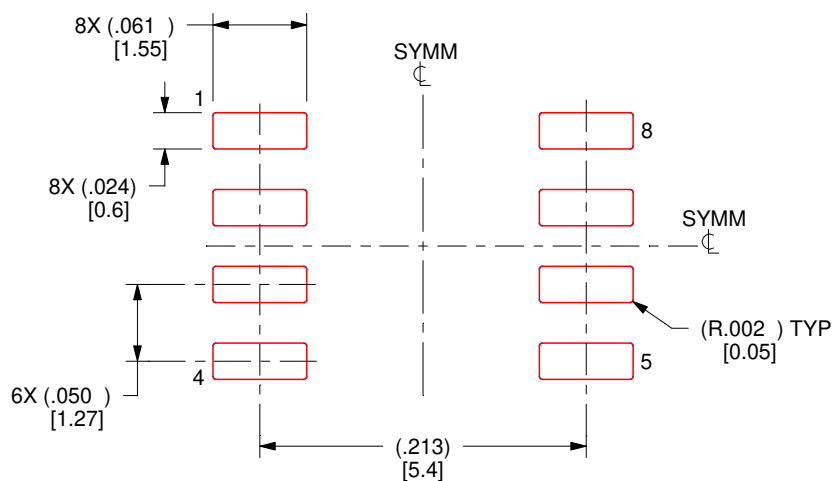
6. Publication IPC-7351 may have alternate designs.

7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

D0008A

SOIC - 1.75 mm max height

SMALL OUTLINE INTEGRATED CIRCUIT



SOLDER PASTE EXAMPLE
BASED ON .005 INCH [0.125 MM] THICK STENCIL
SCALE:8X

4214825/C 02/2019

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

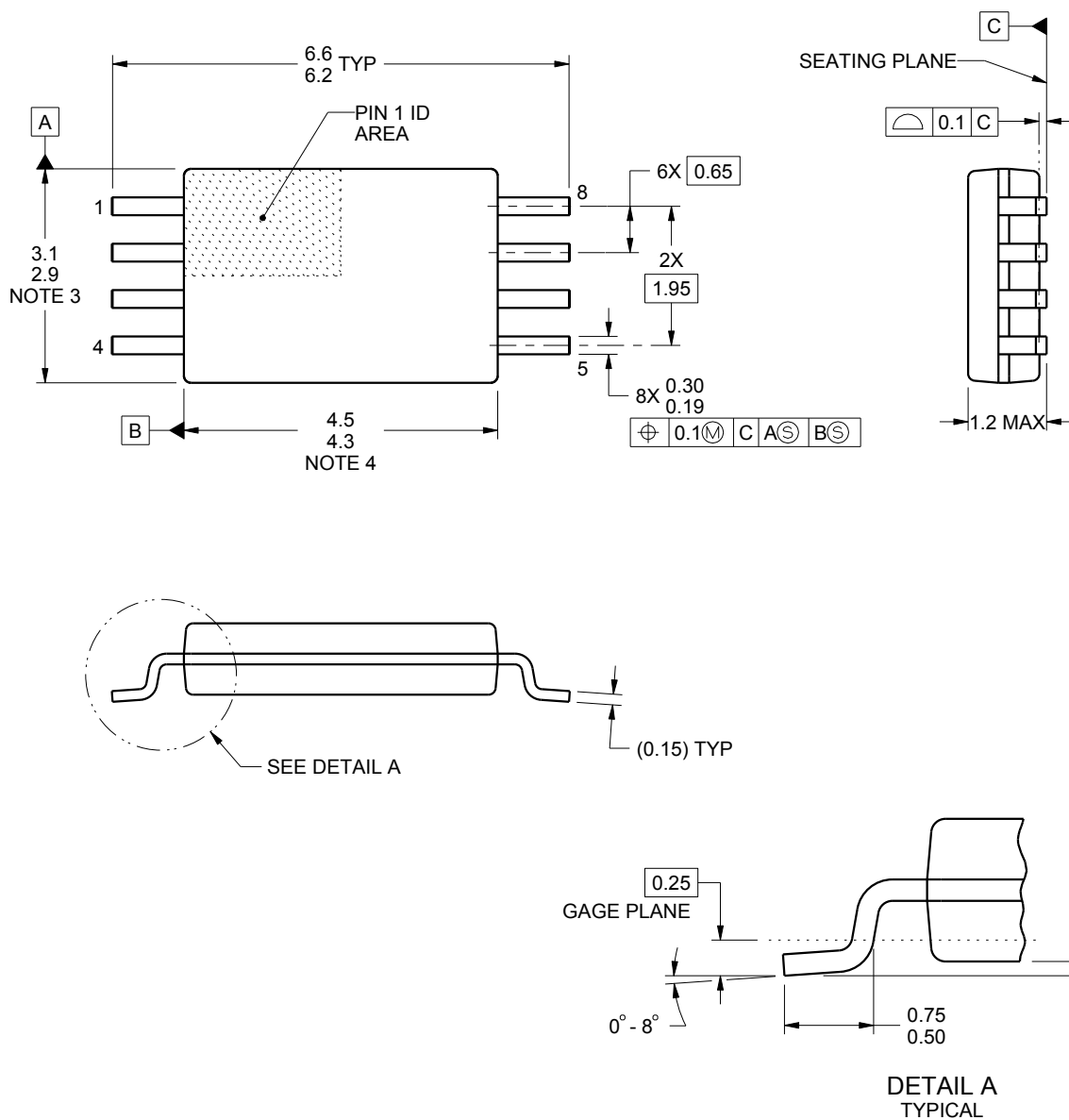
PW0008A



PACKAGE OUTLINE

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



4221848/A 02/2015

NOTES:

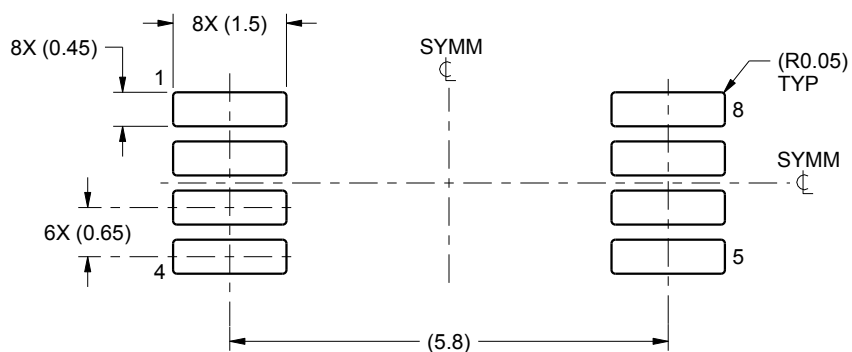
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This dimension does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.15 mm per side.
4. This dimension does not include interlead flash. Interlead flash shall not exceed 0.25 mm per side.
5. Reference JEDEC registration MO-153, variation AA.

EXAMPLE BOARD LAYOUT

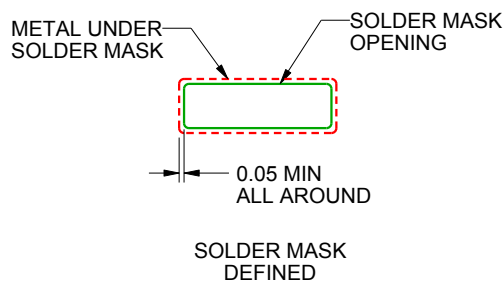
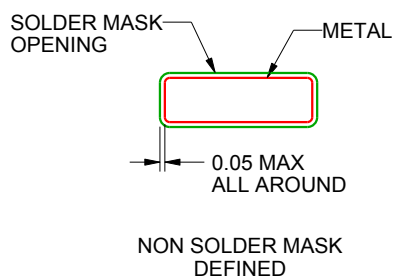
PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



LAND PATTERN EXAMPLE
SCALE:10X



SOLDER MASK DETAILS
NOT TO SCALE

4221848/A 02/2015

NOTES: (continued)

6. Publication IPC-7351 may have alternate designs.

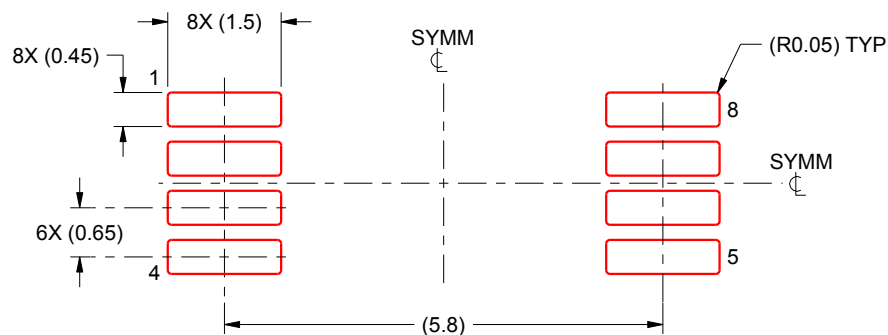
7. Solder mask tolerances between and around signal pads can vary based on board fabrication site.

EXAMPLE STENCIL DESIGN

PW0008A

TSSOP - 1.2 mm max height

SMALL OUTLINE PACKAGE



SOLDER PASTE EXAMPLE
BASED ON 0.125 mm THICK STENCIL
SCALE:10X

4221848/A 02/2015

NOTES: (continued)

8. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.
9. Board assembly site may have different recommendations for stencil design.

IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, regulatory or other requirements.

These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you fully indemnify TI and its representatives against any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to [TI's Terms of Sale](#), [TI's General Quality Guidelines](#), or other applicable terms available either on ti.com or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products. Unless TI explicitly designates a product as custom or customer-specified, TI products are standard, catalog, general purpose devices.

TI objects to and rejects any additional or different terms you may propose.

Copyright © 2026, Texas Instruments Incorporated

Last updated 10/2025